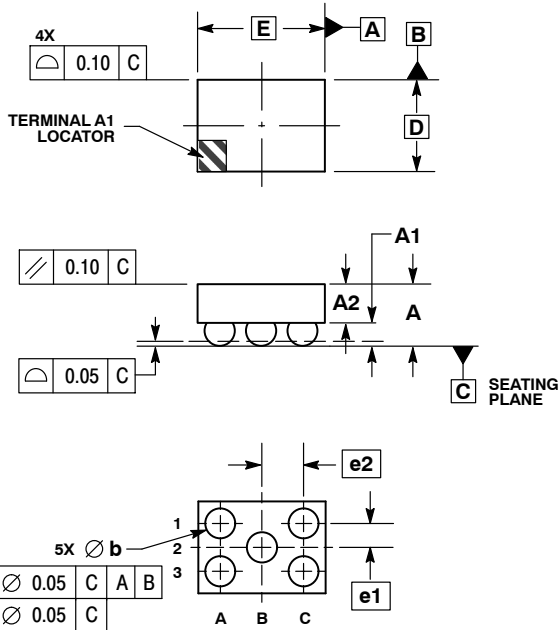




SCALE 4:1

5 PIN FLIP-CHIP
CASE 499AY
ISSUE 0

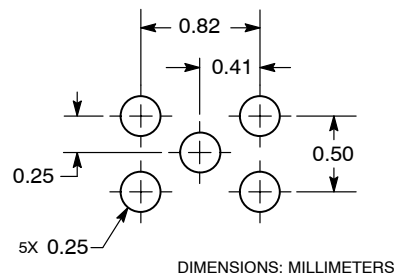
DATE 06 JUN 2007



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.475	0.530	0.585
A1	0.170	0.200	0.230
A2	0.305	0.330	0.355
b	0.220	0.250	0.270
D		1.028 BSC	
E		1.190 BSC	
e1		0.250 BSC	
e2		0.410 BSC	

SOLDERING FOOTPRINT*


*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, [SOLDERRM/D](#).

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DESCRIPTION:	5 PIN FLIP-CHIP, 1.028X1.190	PAGE 1 OF 1

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